

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L1 | 235 | tokyo.asn. and electron.asn. and (heat near4 chamber) and heater | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:49 |
| L2 | 2 | tokyo.asn. and electron.asn. and (recirculating) and (coating near10 solution) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:51 |
| L3 | 1 | tokyo.asn. and electron.asn. and (recirculation) and (coating near10 solution) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:51 |
| L4 | 6 | tokyo.asn. and electron.asn. and (recycling) and (coating near10 solution) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:51 |
| L5 | 6 | ((("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741"))).PN. | USPAT | OR | OFF | 2004/11/15 11:54 |
| L6 | 0 | 5 and (recircul) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:59 |
| L7 | 2 | 5 and (recircul\$) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:54 |
| L8 | 4 | 5 and framework | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 11:59 |

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|-----|---|---|---|----|----|------------------|
| L9 | 5 | 5 and (processor near3 head) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 12:00 |
| L10 | 5 | 5 and ("250") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 12:15 |
| L11 | 0 | 5 and (dissipator) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 12:16 |
| L12 | 0 | 5 and (dissipater) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 12:16 |
| L13 | 0 | 5 and ((heat near4 source) same platform) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 12:16 |
| L14 | 1 | 5 and ((heat near4 chamber)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/15 12:16 |

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|----|----|--|---|----|----|------------------|
| S1 | 49 | US-3641973-\$.DID. OR US-3770598-\$.DID. OR US-3798056-\$.DID. OR US-3950184-\$.DID. OR US-3962047-\$.DID. OR US-3978578-\$.DID. OR US-4027686-\$.DID. OR US-4092176-\$.DID. OR US-4110176-\$.DID. OR US-4113492-\$.DID. OR US-4118303-\$.DID. OR US-4137867-\$.DID. OR US-4170959-\$.DID. OR US-4226208-\$.DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4280882-\$.DID. OR US-4304641-\$.DID. OR US-4315059-\$.DID. OR US-4336114-\$.DID. OR US-4339313-\$.DID. OR US-4339319-\$.DID. OR US-4341613-\$.DID. OR US-4351266-\$.DID. OR US-4373988-\$.DID. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/14 20:49 |
| S2 | 25 | US-3641973-\$.DID. OR US-3770598-\$.DID. OR US-3798056-\$.DID. OR US-3950184-\$.DID. OR US-3962047-\$.DID. OR US-3978578-\$.DID. OR US-4027686-\$.DID. OR US-4092176-\$.DID. OR US-4110176-\$.DID. OR US-4113492-\$.DID. OR US-4118303-\$.DID. OR US-4137867-\$.DID. OR US-4170959-\$.DID. OR US-4226208-\$.DID. OR US-4246088-\$.DID. OR US-4259166-\$.DID. OR US-4280882-\$.DID. OR US-4304641-\$.DID. OR US-4315059-\$.DID. OR US-4336114-\$.DID. OR US-4339313-\$.DID. OR US-4339319-\$.DID. OR US-4341613-\$.DID. OR US-4351266-\$.DID. OR US-4373988-\$.DID. | USPAT; USOCR | OR | ON | 2004/11/14 21:07 |

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| S3 | 27 | US-4376685-\$.DID. OR US-4405416-\$.DID. OR US-4428815-\$.DID. OR US-4435266-\$.DID. OR US-4466864-\$.DID. OR US-4469566-\$.DID. OR US-4489740-\$.DID. OR US-4510176-\$.DID. OR US-4514266-\$.DID. OR US-4518678-\$.DID. OR US-4534832-\$.DID. OR US-4565607-\$.DID. OR US-4597836-\$.DID. OR US-4624749-\$.DID. OR US-4675096-\$.DID. OR US-4693805-\$.DID. OR US-4696729-\$.DID. OR US-4732785-\$.DID. OR US-4750505-\$.DID. OR US-4827867-\$.DID. OR US-4828654-\$.DID. OR US-4838978-\$.DID. OR US-4838979-\$.DID. OR US-4856456-\$.DID. OR US-4856641-\$.DID. OR US-4861452-\$.DID. OR US-4861563-\$.DID. | USPAT; USOCR | OR | ON | 2004/11/14 21:37 |
| S4 | 27 | US-4879007-\$.DID. OR US-4906346-\$.DID. OR US-4924890-\$.DID. OR US-4931149-\$.DID. OR US-5000827-\$.DID. OR US-5024746-\$.DID. OR US-5039381-\$.DID. OR US-5055425-\$.DID. OR US-5069760-\$.DID. OR US-5078852-\$.DID. OR US-5092975-\$.DID. OR US-5096550-\$.DID. OR US-5100502-\$.DID. OR US-5100516-\$.DID. OR US-5155336-\$.DID. OR US-5158100-\$.DID. OR US-5162260-\$.DID. OR US-5169408-\$.DID. OR US-5222310-\$.DID. OR US-5224504-\$.DID. OR US-5227041-\$.DID. OR US-5228966-\$.DID. OR US-5230743-\$.DID. OR US-5238500-\$.DID. OR US-5252807-\$.DID. OR US-5256274-\$.DID. OR US-5259407-\$.DID. | USPAT; USOCR | OR | ON | 2004/11/14 21:14 |

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| S5 | 21 | US-5275976-\$.DID. OR US-5290361-\$.DID. OR US-5294257-\$.DID. OR US-5312487-\$.DID. OR US-5316974-\$.DID. OR US-5328589-\$.DID. OR US-5232328-\$.DID. OR US-5332487-\$.DID. OR US-5235995-\$.DID. OR US-5252137-\$.DID. OR US-5270248-\$.DID. OR US-5340437-\$.DID. OR US-5349978-\$.DID. OR US-5368711-\$.DID. OR US-5372699-\$.DID. OR US-5377708-\$.DID. OR US-5391285-\$.DID. OR US-5405518-\$.DID. OR US-5415890-\$.DID. OR US-5421987-\$.DID. OR US-5429733-\$.DID. | USPAT; USOCR | OR | ON | 2004/11/14 21:14 |
| S6 | 2 | ("4651640").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 21:38 |
| S7 | 2 | ("4651440").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:08 |
| S8 | 2 | ("5156174").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:49 |
| S9 | 2 | ("4590094").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/15 09:19 |
| S10 | 10 | ("3136323" "3494815" "4027686" "4161356" "4745422" "4788994" "4871417" "4922277").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:28 |
| S11 | 109 | "118"/\$.ccls. and polyvinylidene and fluoride | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:29 |

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|-----|------|---|---|----|-----|------------------|
| S12 | 90 | "118"/\$.ccls. and (polyvinylidene near2 fluoride) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:29 |
| S13 | 1 | "118"/\$.ccls. and (polyvinylidene near2 fluoride) and (acid near3 resistant) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:51 |
| S14 | 9 | "118"/\$.ccls. and (polyvinylidene near2 fluoride) and (wafer near3 holder) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:29 |
| S15 | 0 | "118"/\$.ccls. and (polyvinylidene near2 fluoride) and (wafer near3 chuck) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:30 |
| S16 | 1 | "118"/\$.ccls. and (polyvinylidene near2 fluoride) and (semiconductor same chuck) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:31 |
| S17 | 10 | "118"/\$.ccls. and (polyvinylidene near2 fluoride) and (semiconductor same holder) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:31 |
| S18 | 6 | ((("5168887") or ("5235995") or ("5431421") or ("5658387") or ("6066575") or ("6375741"))).PN. | USPAT | OR | OFF | 2004/11/14 22:50 |
| S19 | 44 | semitool and polyvinylidene | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/14 22:51 |
| S20 | 41 | semitool.asn. and (polyvinylidene near2 fluoride) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/11/14 22:51 |
| S21 | 12 | (semiconductor or wafer) and (process\$5 near10 chamber) and (polyvinylidene near2 fluoride) and (acid near3 resistant) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 23:49 |
| S22 | 1409 | (118/52).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:51 |
| S24 | 799 | (118/302).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:52 |

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| S25 | 1656 | (118/323).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:52 |
| S26 | 88 | (118/21).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:52 |
| S27 | 143 | (118/683).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:53 |
| S28 | 287 | (118/667).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:53 |
| S29 | 1171 | (118/300).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:53 |
| S30 | 525 | (118/313).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:53 |
| S31 | 861 | (118/315).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 22:53 |
| S32 | 944 | (118/320).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:28 |
| S33 | 0 | (semiconductor or wafer) and (process\$5 near10 chamber) and (polyvinylidene near2 fluoride) and (acid near3 retardant) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 22:56 |

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| S34 | 1395 | (427/240).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S35 | 2456 | (427/372.2).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S36 | 811 | (427/421).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S37 | 0 | (427/423).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S38 | 567 | (427/425).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S39 | 152 | (427/72).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S40 | 1599 | (427/96).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |
| S41 | 241 | (438/760).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:29 |

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| S42 | 766 | (438/758).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:30 |
| S44 | 510 | (438/782).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:30 |
| S45 | 766 | (134/33).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:30 |
| S46 | 351 | (134/149).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:30 |
| S47 | 1115 | (134/153).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:30 |
| S48 | 638 | (134/157).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:31 |
| S49 | 2240 | (134/902).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:31 |
| S50 | 697 | (134/182).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:31 |

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| S51 | 1050 | (134/200).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:31 |
| S52 | 429 | (134/183).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/11/14 23:31 |
| S53 | 9 | (semiconductor or wafer) and ((process\$5 near10 chamber) same (acid near3 resistant)) | US-PGPUB; USPAT; USOCR | OR | ON | 2004/11/14 23:51 |
| S54 | 2 | ((("4222345") or ("4282825"))).PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2004/11/15 11:26 |